Data Sheet

Ball Grid Array Assembly (BGA)

Advanced Microelectronic Packaging

Complete Turn-Key Production

- Organic (incl. BT), ceramic, or metal substrates
  - All body sizes & configurations
- Custom substrate design & acquisition, or
- Assembly of customer-supplied substrates
- High-performance substrates available
- Low & medium volume production
- Quick-turn prototypes in 8 hours
- Materials selection & evaluation
- Reliability testing
- Inventory management
- ITAR Registered (Reg. Code: M24169)

Wirebond or Flip Chip

- Finest-pitch wirebonding (< 35 μm)
- Ultra-high wire counts
- Stacked die (ultra-thin die)
- Wafer-bumping services available

Sealing

- Dam & fill encapsulation
- Underfill & lid (Flip Chip)
- Open cavity or removable lid

Ball Attach

- Eutectic & High Pb
- Pb-Free (RoHS)
- All ball sizes

Marking

- Custom marking
- Mil Std permanency
- Serialization available

Wafer Dicing

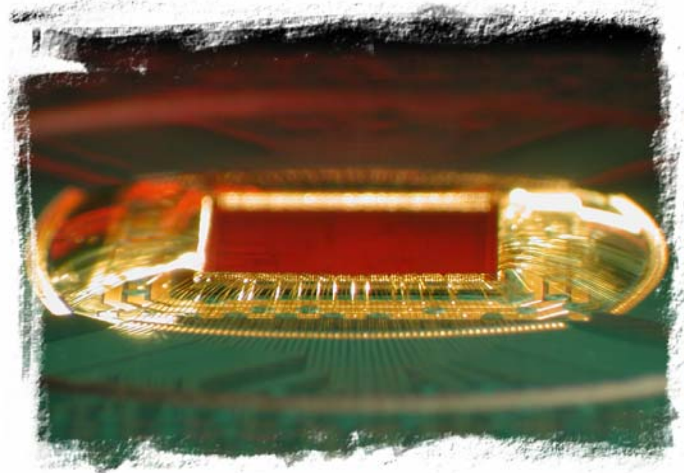
- Up to 300mm wafers
- Thin wafers & narrow streets
- Die and wafer tracing available
- Wafer backgrind available

Aspen Technologies is a preferred on-shore supplier of wirebond and Flip Chip PBGA & CBGA devices. By design, BGAs maximize the performance of today's silicon, but they also require advanced assembly equipment & processes. Aspen Technologies has the latest equipment & the engineering depth to help bring your BGA products to market quickly & with unsurpassed quality!

Whether you need 50 or 500,000 devices, Aspen will work closely with you to provide a full turn-key solution. Aspen can execute the design of standard or high-performance substrates with multiple power & grounds for enhanced performance, source the substrates from the best approved suppliers, and manufacture the substrates in singulated or strip form in our Colorado facilities.

With advance preparation, prototypes of your first silicon can often be made in just 8 hours, & Aspen can ship fully-encapsulated devices or parts with removable lids for additional die processing or probing.

There's a reason why some of the world's most recognizable names in electronics depend on Aspen Technologies for their BGA assembly needs. Let Aspen leverage these same capabilities for your critical BGA projects!



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